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# (12) United States Patent

#### Silverbrook

# (54) HANDHELD IMAGING DEVICE INCORPORATING MULTI-CORE IMAGE PROCESSOR

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#### (58) Field of Classification Search

None

See application file for complete search history.

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#### (57) ABSTRACT

A handheld imaging device includes an image sensor for sensing an image; a processor for processing the sensed image; a plurality of processing units provided in the processor, the plurality of processing units connected in parallel by a crossbar switch to form a multi-core processing unit for the processor; and an image sensor interface for converting signals from the image sensor to a format readable by the plurality of processing units, the image sensor interface sharing a wafer substrate with the processor. A transfer of data from the image sensor interface to the plurality of processing units is conducted entirely on the shared wafer substrate.

#### 18 Claims, 149 Drawing Sheets

